L Number	Hits	Search Text	DB	Time stamp
–	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2004/05/04 11:22
–	11	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with remov$3 with oxide)	USPAT; US-PGPUB	2003/05/30 16:14
–	152	transfer$4 with chamber with remov$3 with oxide	USPAT; US-PGPUB	2003/05/29 20:25
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with "hf")	USPAT; US-PGPUB	2003/05/29 20:29
–	260	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (gas vapor))	USPAT; US-PGPUB	2003/05/29 20:33
–	29	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (gas vapor) with remov$3)	USPAT; US-PGPUB	2003/05/29 20:41
–	2	"11134684"	JPO; DERWENT	2003/05/29 20:49
–	163	sugiura.in. and tokyo.as.	JPO; DERWENT	2003/05/29 20:49
–	6	sugiura.in. and tokyo.as. and "uv"	JPO; DERWENT	2003/05/29 20:49
–	6	("5228206" | "5972161" | "6143081" | "6178660" | "6204120" | "6232248").PN.	USPAT	2003/05/29 20:53
–	2	6178660.URPN.	USPAT	2003/05/29 21:00
–	0	6467491.URPN.	USPAT	2003/05/29 21:00
–	13	("4795299" | "4917556" | "5228206" | "5423971" | "5529657" | "5611861" | "5755938" | "5759334" | "5855675" | "5863170" | "5880924" | "5882165" | "5886864").PN.	USPAT	2003/05/29 21:01
–	112	imahashi.in.	USPAT; US-PGPUB	2003/05/30 10:14
–	2	imahashi.in. and 118/719.ccls.	USPAT; US-PGPUB	2003/05/30 10:15
–	50	5695564.URPN.	USPAT	2003/05/30 10:31
–	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/05/30 10:38
–	94	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (inlet ((vapor gas) with suppl$3)))	USPAT; US-PGPUB	2003/05/30 10:41
–	54	c23c016$.ipc. and (transfer$4 with chamber with (inlet suppl$3) with (vapor gas))	EPO; JPO; DERWENT	2003/05/30 11:21
–	71	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (inlet suppl$3) with (vapor gas))	USPAT; US-PGPUB	2003/05/30 10:51
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((transfer$4 with chamber with (inlet suppl$3) with (vapor gas)) same align$4)	USPAT; US-PGPUB	2003/05/30 10:54
–	0	c23c016$.ipc. and ((transfer$4 with chamber with (inlet suppl$3) with (vapor gas)) same align$4)	EPO; JPO; DERWENT	2003/05/30 10:54
–	1	c23c016$.ipc. and ((transfer$4 with chamber with (inlet suppl$3) with (vapor gas)) and align$4)	EPO; JPO; DERWENT	2003/05/30 10:55
–	33	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((transfer$4 with chamber with (inlet suppl$3) with (vapor gas)) and align$4)	USPAT; US-PGPUB	2003/05/30 11:12
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (teflon ((silicon with carbide) "sic") polytetrafluoroethylene (resin$3 with polymer$3)))	USPAT; US-PGPUB	2003/05/30 11:20
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with (teflon))	USPAT; US-PGPUB	2003/05/30 11:21

–	0	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with ((silicon with carbide) "sic"))	USPAT; US-PGPUB	2003/05/30 11:22
–	0	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with polytetrafluoroethylene)	USPAT; US-PGPUB	2003/05/30 11:21
–	0	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with resin$3 with polymer$3)	USPAT; US-PGPUB	2003/05/30 11:22
–	48150	c23c016$.ipc.	EPO; JPO; DERWENT	2003/05/30 16:32
–	0	c23c016$.ipc. and (transfer$4 with chamber with (teflon))	EPO; JPO; DERWENT	2003/05/30 11:22
–	0	c23c016$.ipc. and (transfer$4 with chamber with polytetrafluoroethylene)	EPO; JPO; DERWENT	2003/05/30 11:24
–	0	c23c016$.ipc. and (transfer$4 with chamber with ((silicon with carbide) "sic"))	EPO; JPO; DERWENT	2003/05/30 11:25
–	0	c23c016$.ipc. and (transfer$4 with chamber with resin$3 with polymer$3)	EPO; JPO; DERWENT	2003/05/30 11:24
–	10	c23c016$.ipc. and (chamber with (teflon))	EPO; JPO; DERWENT	2003/05/30 11:22
–	0	c23c016$.ipc. and (chamber with resin$3 with polymer$3)	EPO; JPO; DERWENT	2003/05/30 11:24
–	6	c23c016$.ipc. and (chamber with polytetrafluoroethylene)	EPO; JPO; DERWENT	2003/05/30 11:24
–	116	c23c016$.ipc. and (chamber with ((silicon with carbide) "sic"))	EPO; JPO; DERWENT	2003/05/30 11:25
–	4	c23c016$.ipc. and (chamber with ((silicon with carbide) "sic") with corros$3)	EPO; JPO; DERWENT	2003/05/30 11:25
–	0	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with "hf")	USPAT; US-PGPUB	2003/05/30 16:30
–	1	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with "acid")	USPAT; US-PGPUB	2003/05/30 16:14
–	0	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with "hydroflouric")	USPAT; US-PGPUB	2003/05/30 16:15
–	1	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with "hydrofluoric")	USPAT; US-PGPUB	2003/05/30 16:15
–	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/05/30 18:05
–	670	transfer$4 with chamber with clean$3 with (wafer substrate semiconductor)	USPAT; US-PGPUB	2003/05/30 16:36
–	48150	c23c016$.ipc.	EPO; JPO; DERWENT	2003/05/30 16:32
–	158	transfer$4 with chamber with clean$3 with (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/05/30 16:32
–	0	c23c016$.ipc. and (transfer$4 with chamber with clean$3 with (wafer substrate semiconductor))	USPAT; US-PGPUB	2003/05/30 16:36
–	12	c23c016$.ipc. and (transfer$4 with chamber with clean$3 with (wafer substrate semiconductor))	EPO; JPO; DERWENT	2003/05/30 16:36
–	91	((((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$4 with chamber with clean$3 with (wafer substrate semiconductor))	USPAT; US-PGPUB	2003/05/30 16:47
–	51	5259881.URPN.	USPAT	2003/05/30 17:00
–	6	("5228206" | "5972161" | "6143081" | "6178660" | "6204120" | "6232248").PN.	USPAT	2003/05/30 17:52
–	3	5972161.URPN.	USPAT	2003/05/30 17:56
–	5	("5240556" | "5344525" | "5554563" | "5670421" | "5830279").PN.	USPAT	2003/05/30 17:58
–	37	transfer with chamber with ("HF" hydrofluoric)	USPAT; US-PGPUB	2003/05/30 18:12

–	5	transfer with chamber with ("HF" hydrofluoric)	EPO; JPO; DERWENT	2003/05/30 18:13
–	46	(US-5766360-$ or US-4816098-$ or US-6027960-$ or US-5939333-$ or US-5897710-$ or US-5877086-$ or US-5271732-$ or US-5236868-$ or US-5202275-$ or US-6467491-$ or US-5981399-$ or US-5551984-$ or US-4426439-$ or US-6178660-$ or US-5972161-$ or US-5695564-$ or US-4883020-$ or US-5462397-$ or US-5474410-$ or US-5527390-$ or US-5740034-$ or US-5609689-$ or US-5879461-$ or US-5882165-$ or US-6143081-$ or US-6528431-$).did. or (US-6140247-$ or US-5043299-$ or US-5259881-$ or US-5294572-$ or US-6007675-$ or US-6323463-$ or US-5770263-$).did. or (US-20030053893-$ or US-20010050146-$ or US-20010031556-$ or US-20010009813-$ or US-20010001298-$ or US-20020034595-$).did. or (JP-2000323425-$ or JP-2002270518-$ or JP-09157073-$ or JP-2002164408-$).did. or (WO-200070666-$ or EP-430303-$ or US-6007675-$).did.	USPAT; US-PGPUB; JPO; DERWENT	2003/05/30 18:15
–	18	((US-5766360-$ or US-4816098-$ or US-6027960-$ or US-5939333-$ or US-5897710-$ or US-5877086-$ or US-5271732-$ or US-5236868-$ or US-5202275-$ or US-6467491-$ or US-5981399-$ or US-5551984-$ or US-4426439-$ or US-6178660-$ or US-5972161-$ or US-5695564-$ or US-4883020-$ or US-5462397-$ or US-5474410-$ or US-5527390-$ or US-5740034-$ or US-5609689-$ or US-5879461-$ or US-5882165-$ or US-6143081-$ or US-6528431-$).did. or (US-6140247-$ or US-5043299-$ or US-5259881-$ or US-5294572-$ or US-6007675-$ or US-6323463-$ or US-5770263-$).did. or (US-20030053893-$ or US-20010050146-$ or US-20010031556-$ or US-20010009813-$ or US-20010001298-$ or US-20020034595-$).did. or (JP-2000323425-$ or JP-2002270518-$ or JP-09157073-$ or JP-2002164408-$).did. or (WO-200070666-$ or EP-430303-$ or US-6007675-$).did.) and (oxide with (remov$3 clean$3) with chamber)	USPAT; US-PGPUB	2003/05/30 18:24

—	3	((US-5766360-$ or US-4816098-$ or US-6027960-$ or US-5939333-$ or US-5897710-$ or US-5877086-$ or US-5271732-$ or US-5236868-$ or US-5202275-$ or US-6467491-$ or US-5981399-$ or US-5551984-$ or US-4426439-$ or US-6178660-$ or US-5972161-$ or US-5695564-$ or US-4883020-$ or US-5462397-$ or US-5474410-$ or US-5527390-$ or US-5740034-$ or US-5609689-$ or US-5879461-$ or US-5882165-$ or US-6143081-$ or US-6528431-$).did. or (US-6140247-$ or US-5043299-$ or US-5259881-$ or US-5294572-$ or US-6007675-$ or US-6323463-$ or US-5770263-$).did. or (US-20030053893-$ or US-20010050146-$ or US-20010031556-$ or US-20010009813-$ or US-20010001298-$ or US-20020034595-$).did. or (JP-2000323425-$ or JP-2002270518-$ or JP-09157073-$ or JP-2002164408-$).did. or (WO-200070666-$ or EP-430303-$ or US-6007675-$).did.) and (transfer$3 same rotat$3 same align$3)	USPAT; US-PGPUB	2003/05/30 18:24
—	0	(c23c016$.ipc. h011021$.ipc.) same (outlet with plural$3 with (even$3))	EPO; JPO; DERWENT	2003/06/02 08:30
—	2	(transfer with chamber) same (outlet with plural$3 with (even$3))	USPAT; US-PGPUB	2003/06/02 08:22
—	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/06/02 08:23
—	0	("5 and ((gas vapor) with (plural$3 multipl$3) with even$3)").PN.	USPAT; US-PGPUB	2003/06/02 08:28
—	16	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((gas vapor) with (plural$3 multipl$3) with even$3)	USPAT; US-PGPUB	2003/06/02 08:27
—	145	(118/$.ccls. 156/345.$.ccls.) and ((gas vapor) with (plural$3 multipl$3) with even$3)	USPAT; US-PGPUB	2003/06/02 08:28
—	175	(c23c016$.ipc. h011021$.ipc.)and ((gas vapor) with (plural$3 multipl$3) with even$3)	USPAT; US-PGPUB	2003/06/02 08:28
—	0	(c23c016$.ipc. h011021$.ipc.)and ((gas vapor) with (plural$3 multipl$3) with even$3)	EPO; JPO; DERWENT	2003/06/02 08:30
—	0	(c23c016$.ipc. h011021$.ipc.)and ((gas vapor) with (plural$3 multipl$3) with (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
—	0	(c23c016$.ipc. h011021$.ipc.)and ((gas vapor) same (plural$3 multipl$3) same (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
—	0	(c23c016$.ipc. h011021$.ipc.) and ((gas vapor) same (plural$3 multipl$3) same (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
—	48150	c23c016$.ipc.	EPO; JPO; DERWENT	2003/06/02 08:30
—	742155	h011021$.ipc.	EPO; JPO; DERWENT	2003/06/02 08:30
—	0	(c23c016$.ipc. h011021$.ipc.) same (outlet with plural$3 with (even$3))	EPO; JPO; DERWENT	2003/06/02 09:10
—	5	(c23c016$.ipc. h011021$.ipc.) and (outlet with plural$3 with (even$3))	EPO; JPO; DERWENT	2003/06/02 08:31
—	82	(c23c016$.ipc. h011021$.ipc.)and ((gas vapor) with (plural$3 multipl$3) with even$3)	EPO; JPO; DERWENT	2003/06/02 08:32
—	70	118/$.ccls. and (oxide with remov$3)	EPO; JPO; DERWENT	2003/06/02 09:11
—	667	118/$.ccls. and (oxide with remov$3)	USPAT; US-PGPUB	2003/06/02 09:11
—	159	118/$.ccls. and (oxide with remov$3 with chamber)	USPAT; US-PGPUB	2003/06/02 09:12
—	27	118/$.ccls. and (oxide with remov$3 with chamber with transfer$4)	USPAT; US-PGPUB	2003/06/02 09:13

–	.	151	((transfer$4 transport$4) with chamber with (substrate wafer semiconductor) with (vapor$4))	EPO; JPO; DERWENT	2003/11/20 13:49
–		624	((transfer$4 transport$4) with chamber with (substrate wafer semiconductor) with (vapor$4))	USPAT; US-PGPUB	2003/11/20 13:38
–		68	("transfer chamber" with (substrate wafer semiconductor) with (vapor$4))	USPAT; US-PGPUB	2003/11/20 13:38
–		17	((transfer$4 adj chamber) with (substrate wafer semiconductor) with (vapor$4))	EPO; JPO; DERWENT	2003/11/20 14:26
–		0	("transfer$4 chamber" with (vapor$4))	EPO; JPO; DERWENT	2003/11/20 14:01
–		161	("transfer chamber" with (vapor$4))	USPAT; US-PGPUB	2003/11/20 14:21
–		37	("transfer chamber" with (vapor$4) with (expos$3 introduc$3 inlet outlet supplied supply$3))	USPAT; US-PGPUB	2003/11/20 14:04
–		124	(("transfer chamber" with (vapor$4))) not (("transfer chamber" with (vapor$4) with (expos$3 introduc$3 inlet outlet supplied supply$3)))	USPAT; US-PGPUB	2003/11/20 14:21
–		1811	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/11/20 15:04
–		8	(vapor with (supply$3 suppli$3) with transfer$4) and (((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.)	USPAT; US-PGPUB	2003/11/20 14:25
–		0	"vapor inlet" with "transfer chamber"	EPO; JPO; DERWENT	2003/11/20 14:27
–		0	"vapor inlet" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
–		1	"vapor port" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
–		0	"vapor hole" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
–		2	"vapor outlet" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:28
–		5	(vapor$4 adj (inlet hole port outlet conduit entrance introduc$3 outlet aperture opening exit orifice vent$3)) with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:31
–		6	("4490209" | "5007982" | "5605603" | "5854137" | "5874362" | "6242350").PN.	USPAT	2003/11/20 14:32
–		6	(vapor$4 with (inlet hole port outlet conduit entrance introduc$3 outlet aperture opening exit orifice vent$3)) with "transfer chamber"	EPO; JPO; DERWENT	2003/11/20 14:34
–		25	(vapor$4 with (inlet hole port outlet conduit entrance introduc$3 outlet aperture opening exit orifice vent$3) with transfer$4) and c23c016$.ipc.	EPO; JPO; DERWENT	2003/11/20 14:41
–		32	427/335.ccls.	EPO; JPO; DERWENT	2003/11/20 14:42
–		3	427/335.ccls. and (transfer$3 with chamber)	USPAT; US-PGPUB	2003/11/20 14:42
–		208	427/335.ccls.	USPAT; US-PGPUB	2003/11/20 14:45
–		19	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (("hydrofluoric acid" "hf") with vapor$4)	USPAT; US-PGPUB	2003/11/20 15:55
–		2	118/719.ccls. and imahashi.in.	USPAT; US-PGPUB	2003/11/20 15:00
–		0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with (vaporiser vaporizer))	USPAT; US-PGPUB	2003/11/20 15:05
–		0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$3 with chamber with (vaporiser vaporizer))	USPAT; US-PGPUB	2003/11/20 15:07
–		10	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$3 with chamber with remov$4 with oxide)	USPAT; US-PGPUB	2003/11/20 15:09

–	39	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer$3 with chamber with oxide)	USPAT; US-PGPUB	2003/11/20 15:09
–	16	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with oxide)	USPAT; US-PGPUB	2003/11/20 15:14
–	92	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with gas)	USPAT; US-PGPUB	2003/11/20 15:18
–	9	c23c016$.ipc. and ("transfer chamber" with (remov$3 clean$3))	EPO; JPO; DERWENT	2003/11/20 15:19
–	79	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with (remov$3 clean$3))	USPAT; US-PGPUB	2003/11/20 15:49
–	6	("5228206" | "5972161" | "6143081" | "6178660" | "6204120" | "6232248").PN.	USPAT	2003/11/20 15:38
–	3	5972161.URPN.	USPAT	2003/11/20 15:39
–	0	6467491.URPN.	USPAT	2003/11/20 15:39
–	13	("4795299" | "4917556" | "5228206" | "5423971" | "5529657" | "5611861" | "5755938" | "5759334" | "5855675" | "5863170" | "5880924" | "5882165" | "5886864").PN.	USPAT	2003/11/20 15:42
–	0	6467491.URPN.	USPAT	2003/11/20 15:43
–	6	("5228206" | "5972161" | "6143081" | "6178660" | "6204120" | "6232248").PN.	USPAT	2003/11/20 15:43
–	11	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with etch)	USPAT; US-PGPUB	2003/11/20 15:51
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with "pre-process")	USPAT; US-PGPUB	2003/11/20 15:52
–	3	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with "pre-processing")	USPAT; US-PGPUB	2003/11/20 15:52
–	0	(((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (("hydrofluoric acid" "hf") with "transfer chamber")	USPAT; US-PGPUB	2003/11/20 15:58
–	195	118/$.ccls. and (transfer$4 with chamber with expos$4)	USPAT; US-PGPUB	2003/11/20 15:59
–	49	118/$.ccls. and (transfer$4 adj chamber with expos$4)	USPAT; US-PGPUB	2003/11/20 15:59
–	49	118/$.ccls. and ((transfer$4 adj chamber) with expos$4)	USPAT; US-PGPUB	2003/11/20 16:04
–	1	118/$.ccls. and ((transfer$4 adj chamber) with acid)	USPAT; US-PGPUB	2003/11/20 16:04
–	1	("5043299").PN.	USPAT; US-PGPUB	2003/11/21 10:55

–	64	(US-5766360-$ or US-4816098-$ or US-6528431-$ or US-6140247-$ or US-6027960-$ or US-5939333-$ or US-5897710-$ or US-5877086-$ or US-5271732-$ or US-5236868-$ or US-5202275-$ or US-5043299-$ or US-6467491-$ or US-6083566-$ or US-5981399-$ or US-5551984-$ or US-4883020-$ or US-4426439-$ or US-6178660-$ or US-6143081-$ or US-5972161-$ or US-5882165-$ or US-5695564-$ or US-6183564-$ or US-5879461-$ or US-5740034-$).did. or (US-5609689-$ or US-5527390-$ or US-5474410-$ or US-5462397-$ or US-6039811-$ or US-6007675-$ or US-5294572-$ or US-5259881-$ or US-6323463-$ or US-5770263-$ or US-4565157-$ or US-4262631-$ or US-5314574-$ or US-6578589-$ or US-6221742-$ or US-6132564-$ or US-6358859-$ or US-4386119-$ or US-4834020-$).did. or (US-20030053893-$ or US-20010031556-$ or US-20010009813-$ or US-20010001298-$ or US-20010050146-$ or US-20020034595-$ or US-20020069899-$ or US-20020020429-$ or US-20010017103-$ or US-20020184896-$).did. or (JP-2000323425-$ or JP-2002270518-$ or JP-09157073-$ or JP-2002164408-$ or JP-61054628-$).did. or (WO-200070666-$ or US-6007675-$ or EP-430303-$ or US-20010031556-$).did.	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 13:22
–	291	(427/$.ccls. 438/$.ccls.) and (transfer$4 with chamber with vapor$4)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:03
–	38	(427/$.ccls. 438/$.ccls.) and ((transfer$4 adj chamber) with vapor$4)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:03
–	40	(427/$.ccls. 438/$.ccls.) and ((transfer$4 adj chamber) with (vapor$4 "hf" "hydrofluoric" "hydrogen fluoride"))	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:19
–	6	("4490209" | "5007982" | "5605603" | "5854137" | "5874362" | "6242350").PN.	USPAT	2003/11/21 11:11
–	1	(427/$.ccls. 438/$.ccls.) and ((transfer$4 adj chamber) with ("etching gas"))	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:21
–	1	(427/$.ccls. 438/$.ccls.) and ((transfer$4 adj chamber) with (etch$3 with (while during)))	USPAT; US-PGPUB	2003/11/21 11:23
–	25	(427/$.ccls. 438/$.ccls.) and ((transfer$4 adj chamber) with (remov$3 with (layer film coating)))	USPAT; US-PGPUB	2003/11/21 11:24
–	8	(118/715-733.ccls. 156/345.$.ccls.) and ((transfer$4 adj chamber) with (remov$3 with (layer film coating)))	USPAT; US-PGPUB	2003/11/21 11:29
–	44	5314574.URPN.	USPAT	2003/11/21 11:39
–	4	("4654106" | "4857142" | "5169408" | "5248380").PN.	USPAT	2003/11/21 11:49
–	0	"09758610"	USPAT; US-PGPUB	2003/11/21 12:37
–	1	"09/758,610"	USPAT; US-PGPUB	2003/11/21 12:41
–	1	("6178660").PN.	USPAT; US-PGPUB	2003/11/21 12:41

–	2	((US-5766360-$ or US-4816098-$ or US-6528431-$ or US-6140247-$ or US-6027960-$ or US-5939333-$ or US-5897710-$ or US-5877086-$ or US-5271732-$ or US-5236868-$ or US-5202275-$ or US-5043299-$ or US-6467491-$ or US-6083566-$ or US-5981399-$ or US-5551984-$ or US-4883020-$ or US-4426439-$ or US-6178660-$ or US-6143081-$ or US-5972161-$ or US-5882165-$ or US-5695564-$ or US-6183564-$ or US-5879461-$ or US-5740034-$).did. or (US-5609689-$ or US-5527390-$ or US-5474410-$ or US-5462397-$ or US-6039811-$ or US-6007675-$ or US-5294572-$ or US-5259881-$ or US-6323463-$ or US-5770263-$ or US-4565157-$ or US-4262631-$ or US-5314574-$ or US-6578589-$ or US-6221742-$ or US-6132564-$ or US-6358859-$ or US-4386119-$ or US-4834020-$).did. or (US-20030053893-$ or US-20010031556-$ or US-20010009813-$ or US-20010001298-$ or US-20010050146-$ or US-20020034595-$ or US-20020069899-$ or US-20020020429-$ or US-20010017103-$ or US-20020184896-$).did. or (JP-2000323425-$ or JP-2002270518-$ or JP-09157073-$ or JP-2002164408-$ or JP-61054628-$).did. or (WO-200070666-$ or US-6007675-$ or EP-430303-$ or US-20010031556-$).did.) and (transfer with chamber with align)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 14:02
–	0	pas-sylvia.in.	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 14:02
–	1	pas-sylvia-h.in.	USPAT; US-PGPUB	2003/11/21 14:03
–	3	pas-sylvia-$.in.	USPAT; US-PGPUB	2003/11/21 14:03
–	1	("6391148").PN.	USPAT; US-PGPUB	2003/11/21 15:09
–	29	("transfer chamber" "transferring chamber") with vapor$3	EPO; JPO; DERWENT	2004/05/04 11:23
–	174	("transfer chamber" "transferring chamber") with vapor$3	USPAT; US-PGPUB	2004/05/04 12:00
–	116	(("transfer chamber" "transferring chamber") with vapor$3) and (substrate wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:02
–	117	(("transfer chamber" "transferring chamber") with vapor$3) and (substrate wafer workpiece semiconductor)	USPAT; US-PGPUB	2004/05/04 12:03
–	0	(((vapor$3 with solution) bubbler) with (transfer$3 adj chamber)) and (414/$.ccls. 118/$.ccls. 216/$.ccls. 427/$.ccls.)	USPAT; US-PGPUB	2004/05/04 12:05
–	8	(((vapor$3 with solution) bubbler) with (transfer$3 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
–	8	(((vapor$3 with solution) bubbler) with (transfer$4 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
–	8	(((vapor$3 with solution) bubbler) with (transfer$4 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
–	4	(((vapor$3 with solution) bubbler) with (transfer$4 adj chamber))	EPO; JPO; DERWENT	2004/05/04 12:10
–	180	(((solution)) with (transfer$4 adj chamber))	EPO; JPO; DERWENT	2004/05/04 12:10
–	116	(((solution)) with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:28
–	127	(gas$4 with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:11

–	14	(gas$4 with solution with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:27
–	0	(gas$4 with solution with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:15
–	37	(solution with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:16
–	3	5983909.URPN.	USPAT	2004/05/04 12:19
–	3	5983909.URPN.	USPAT	2004/05/04 12:19
–	4	("5599438" | "5616221" | "5635053" | "5676760").PN.	USPAT	2004/05/04 12:19
–	11	6039815.URPN.	USPAT	2004/05/04 12:20
–	6	("5190627" | "5599438" | "5616221" | "5635053" | "5676760" | "5806126").PN.	USPAT	2004/05/04 12:21
–	0	"vaporous solution"	EPO; JPO; DERWENT	2004/05/04 12:27
–	0	(bubbler with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:29
–	1	(bubbler with (transfer$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:28
–	0	(vapor with (transfer$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:30
–	1	((transfer$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:31
–	5	(. (transfer$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:32
–	0	((transfer$4 adj chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:33
–	4	((transfer$4 adj chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:34
–	195	(((transfer$4 transport$3) with chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:24
–	397	(((transfer$4 transport$3) adj chamber) with (clean$3)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:25
–	8	(((transfer$4 transport$3) adj chamber) with (clean$3) with vapor$3) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:28
–	397	(((transfer$4 transport$3) adj chamber) with (clean$3)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:28
–	45	5314574.URPN.	USPAT	2004/05/04 13:31
–	116	(156/345.31.ccls. 156/345.32.ccls. 414/935-939.ccls. 118/719.ccls. 204/298.25.ccls. 204/298.26.ccls. 204/298.35.ccls.) and (((transfer$4 transport$3) adj chamber) same (solution aqueous liquid vapor$3))	USPAT; US-PGPUB	2004/05/04 14:48
–	764	"hf vapor"	USPAT; US-PGPUB	2004/05/04 14:48
–	34	"hf vapor" and ((transfer$4 transport$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:48
–	0	"hbr vapor" and ((transfer$4 transport$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:48
–	0	("hbr vapor" "hbr vapor" "hcl vapor") with ((transfer$4 transport$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:49
–	3	("hbr vapor" "hbr vapor" "hcl vapor") with (transfer$4 transport$3) with chamber	USPAT; US-PGPUB	2004/05/04 14:53
–	0	("hbr vapor" "hbr vapor" "hcl vapor") with (transfer$4 transport$3) with chamber	EPO; JPO; DERWENT	2004/05/04 14:52
–	5	("hbr" "hbr" "hcl") with vapor with (transfer$4 transport$3) with chamber	USPAT; US-PGPUB	2004/05/04 14:53

–	5	("hbr" "hbr" "hcl") with vapor$5 with (transfer$4 transport$3) with chamber	USPAT; US-PGPUB	2004/05/04 14:56
–	6	("4490209" | "5007982" | "5605603" | "5854137" | "5874362" | "6242350").PN.	USPAT	2004/05/04 14:55
–	1	("hbr" "hbr" "hcl") with vapor$5 with (transfer$4 transport$3) with chamber	EPO; JPO; DERWENT	2004/05/04 14:57
–	8	(acid$2) with vapor$5 with (transfer$4 transport$3) with chamber	EPO; JPO; DERWENT	2004/05/04 15:05
–	28	(acid$2) with vapor$5 with (transfer$4 transport$3) with chamber	USPAT; US-PGPUB	2004/05/04 15:43
–	404	kondo.in. and oxide and vapor	USPAT; US-PGPUB	2004/05/04 15:43
–	83	kondo.in. and oxide and vapor	EPO; JPO; DERWENT	2004/05/04 15:43
–	47	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece)	EPO; JPO; DERWENT	2004/05/04 15:44
–	8	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece) and acid$3	EPO; JPO; DERWENT	2004/05/04 15:49
–	182	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece) and acid$3	USPAT; US-PGPUB	2004/05/04 15:49
–	4	kondo.in. and (oxide same vapor same (substrate wafer semiconductor workpiece) same acid$3)	USPAT; US-PGPUB	2004/05/04 15:52
–	43	5303671.URPN.	USPAT	2004/05/04 15:51
–	1	"4592306".PN.	USPAT	2004/05/04 15:51
–	0	(("hbr vapor" "hbr vapor" "hcl vapor") with (transfer$4 transport$3) with chamber) and (vapor$3 same acid$3)	USPAT; US-PGPUB	2004/05/04 15:53
–	0	(("hbr vapor" "hbr vapor" "hcl vapor") with (transfer$4 transport$3) with chamber) and (acid$3)	USPAT; US-PGPUB	2004/05/04 15:52
–	0	((("hbr vapor" "hbr vapor" "hcl vapor") with (transfer$4 transport$3) with chamber) and (vapor$3 same acid$3)) and (vapor$3 same acid$3)	USPAT; US-PGPUB	2004/05/04 15:52
–	2	5303671.URPN. and (vapor$3 same acid$3)	USPAT; US-PGPUB	2004/05/04 15:53
–	7	5303671.URPN. and (acid$3)	USPAT; US-PGPUB	2004/05/04 15:55
–	18	5303671.URPN. and (vapor$3)	USPAT; US-PGPUB	2004/05/04 15:56
–	2	5303671.URPN. and (vapor$3 with (transfer$4 transport$4))	USPAT; US-PGPUB	2004/05/04 17:00
–	1	"4592306".PN.	USPAT	2004/05/04 16:10
–	43	5303671.URPN.	USPAT	2004/05/04 16:10
–	1	10/265,899	USPAT; US-PGPUB	2004/05/04 17:01
–	1	10/265,699	USPAT; US-PGPUB	2004/05/04 17:01
–	1	414/936.ccls. and (vapor$3 with (acid "HF" "Hbr" "HCL"))	USPAT; US-PGPUB	2004/05/05 12:16
–	11	5474641.URPN.	USPAT	2004/05/05 12:27
–	173	(oxide with remov$3) with transfer$4 with chamber	USPAT; US-PGPUB	2004/05/05 12:16